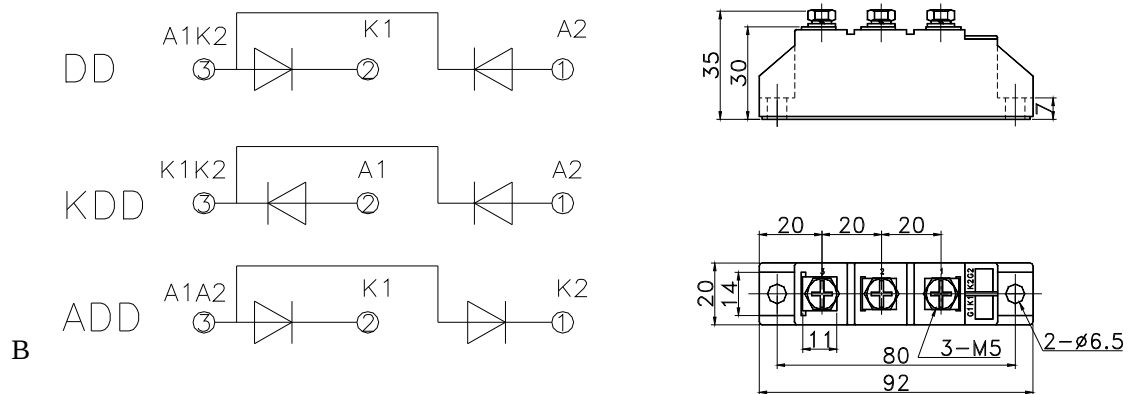


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SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			55	A
I _{F(RMS)}	RMS forward current	Single side cooled, T _C =100°C	150			86	A
V _{RRM}	Repetitive peak reverse voltage	V _{RRM} tp=10ms V _{RSM} = V _{DRM} &V _{RRM} +200V	150	600		1800	V
I _{RRM}	Repetitive peak current	at V _{RRM}	150			8	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			1.30	KA
I ² t	I ² T for fusing coordination	V _R =0.6V _{RRM}				8.6	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.80	V
r _F	Forward slop resistance					3.47	mΩ
V _{FM}	Peak forward voltage	I _{FM} =165A	25			1.45	V
R _{th(j-c)}	Thermal resistance Junction to heatsink	At 180° sine Single side cooled				0.700	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(max)		2500			V
F _m	Terminal connection torque(M5)				2.0		N·m
	Mounting torque(M6)				3.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				100		g
Outline	201F3						

OUTLINE DRAWING & CIRCUIT DIAGRAM



Peak forward Voltage Vs. Peak forward Current

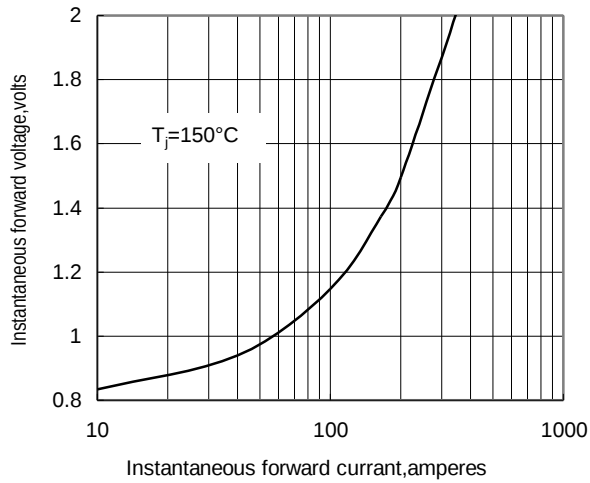


Fig.1

Max. junction To case Thermal Impedance Vs. Time

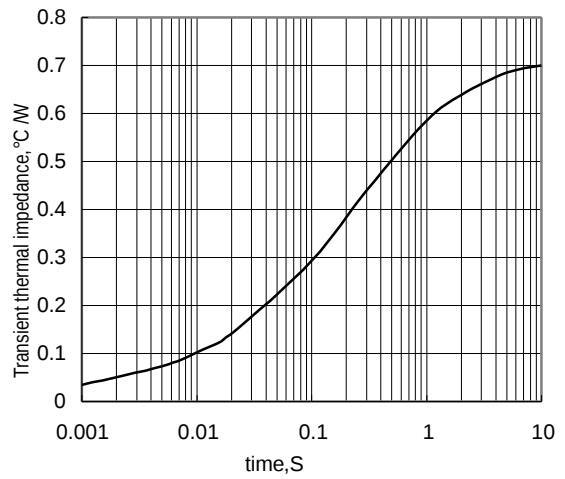


Fig.2

Max. Power Dissipation Vs. Mean forward Current

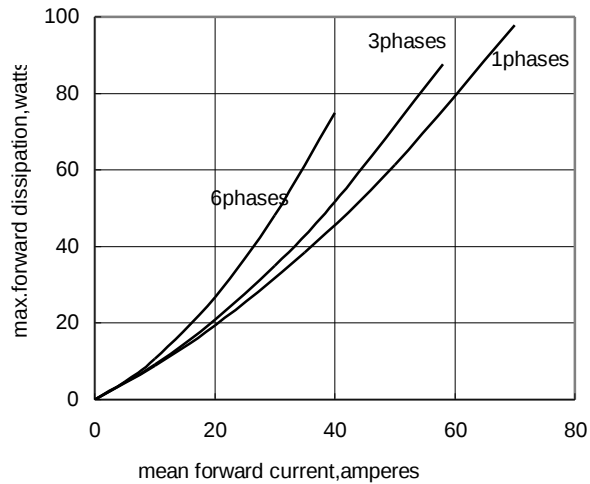


Fig.3

Max. case Temperature Vs. Mean forward Current

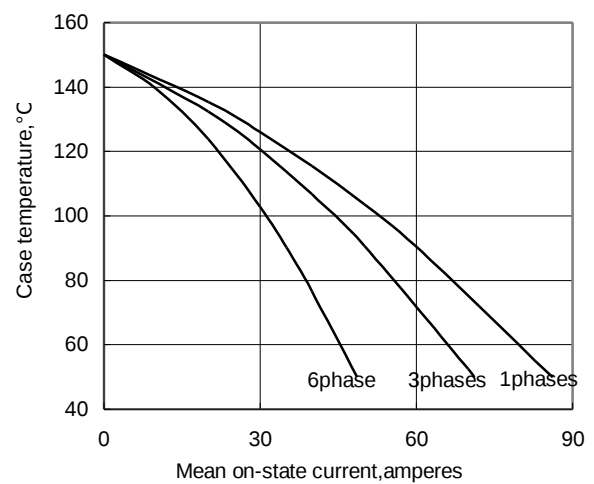


Fig.4

Max. Power Dissipation Vs. Mean forward Current

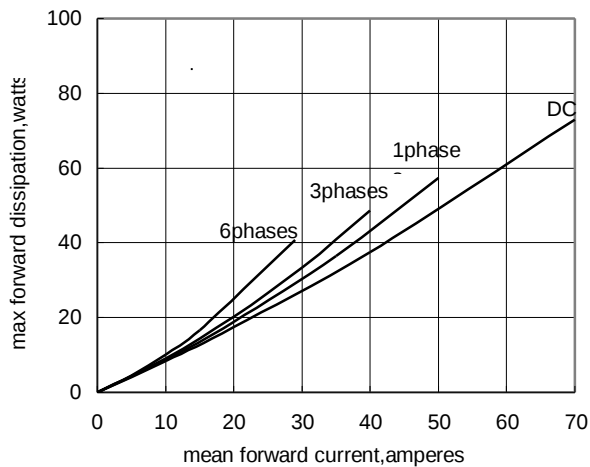


Fig.5

Max. case Temperature Vs. Mean forward Current

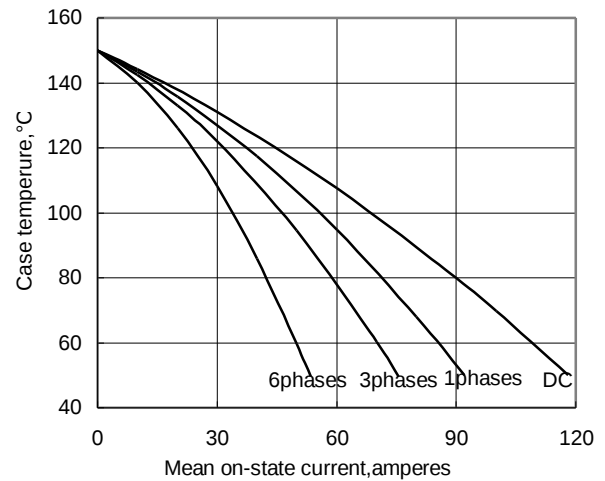


Fig.6